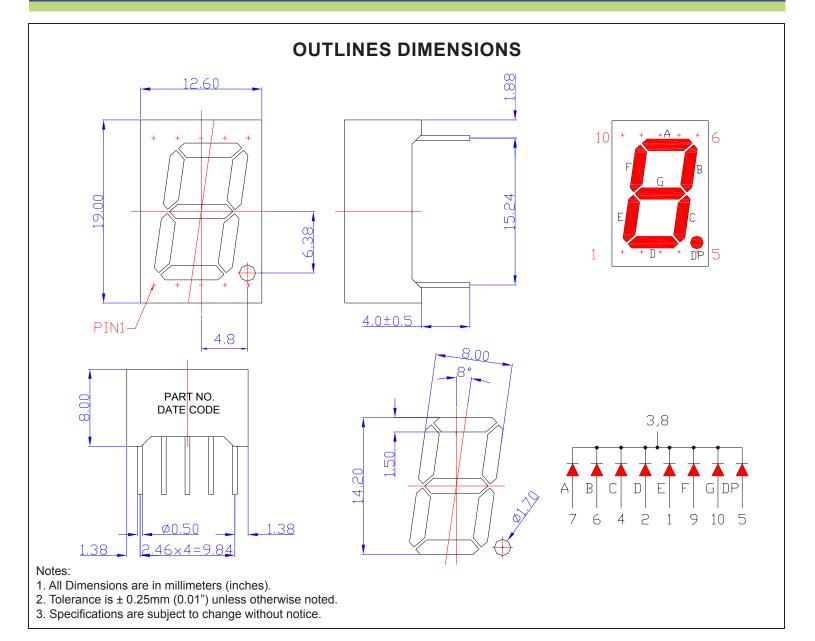


SPECIFICATIONS

CDSC56RR1WBF



Part Number	Chip Material	Color of Emission	Segment/Face	Description	
CDSC56RR1WBF	AlGaAs	Red	White/Black	Common Cathode	





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit			
Power Dissipation	PD	75	mW			
Pulse Forward Current	lfp	200	mA			
Continuous Forward Current	lF	30	mA			
Reverse Voltage Segment	VR	5	V			
Operating Temperature Range	Topr	-25~+85	°C			
Storage Temperature Range	Tstg	-25~+85	°C			
IFP = Pulse Width \leq 10 ms, Duty Ratio \leq 1/10. Soldering Condition: 260 °C/ 5sec						

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Deremeter	Symbol	Test Condition	Value			Lloit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	lv	l⊧ = 20mA	-	6	-	mcd
Forward Voltage	Vf	l⊧ = 20mA	-	1.8	2.6	V
Reverse Leakage Current	lr	V _R = 5V	-	-	10	μA
Peak Wavelength	λP	l⊧ = 20mA	-	655	-	nm
Dominant Wavelength	λD	l⊧ = 20mA	-	644	-	nm
Spectral Radiation Bandwidth	Δλ	l⊧ = 20mA	-	20	-	nm





OPTICAL CHARACTERISTIC CURVES

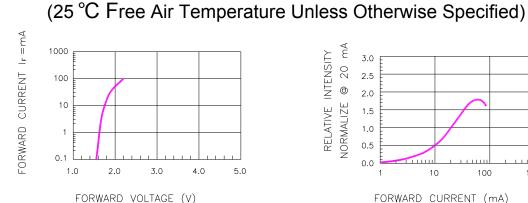


Fig.1 FORWARD CURRENT VS. FORWARD VOLTAGE

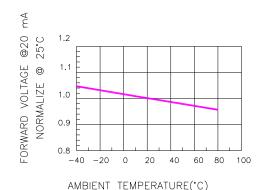


Fig.3 FORWARD VOLTAGE VS. TEMPERATURE

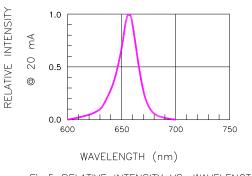
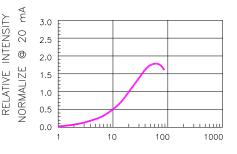


Fig.5 RELATIVE INTENSITY VS. WAVELENGTH



FORWARD CURRENT (mA) Fig.2 RELATIVE INTENSITY VS. FORWARD CURRENT

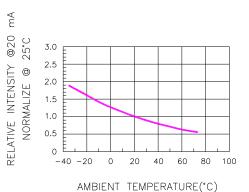
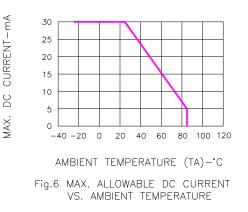


Fig.4 RELATIVE INTENSITY VS. TEMPERATURE

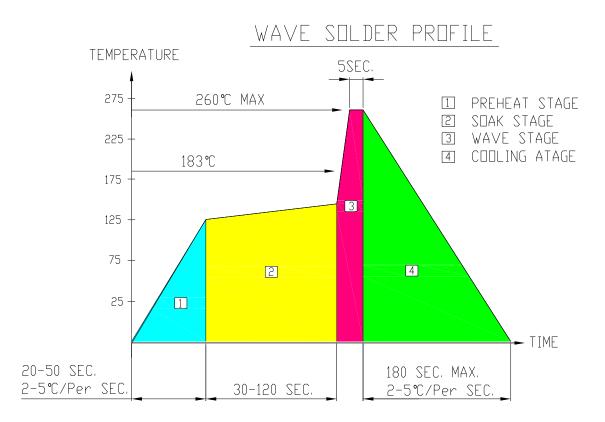






SOLDERING CONDITIONS – DISPLAY TYPE LED

• RECOMMEND SOLDERING PROFILE



SOLDERING IRON

Basic spec is \leq 4 sec when 260°C. If temperature is higher, time should be shorter (+10°C→1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

REWORK

Customer must finish rework within ≦4 sec under 245°C.

